

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MITSUI HIGH-TEC, INC.	09/27/2018
RECEIVING PARTY DATA	
Name:	ADVANCED SEMICONDUCTOR ENGINEERING, INC.
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City:	KAOHSIUNG
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 3	
Property Type	Number
Patent Number:	8680657
Patent Number:	8349656
Patent Number:	8258608
CORRESPONDENCE DATA	
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SIGNATURE:	/Cliff Z. Liu/
DATE SIGNED:	10/01/2018
Total Attachments: 2	
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PATENT ASSIGNMENT

WHEREAS MITSUI HIGH-TEC, INC., of 10-1, KOMINE 2-CHOME, YAHATANISHI-KU, KITAKYUSHU-SHI, FUKUOKA, JAPAN 807-8588, (hereinafter "Assignor") is the owner of the following United States Letters Patents, and the inventions set forth therein, as shown by the records of the United States Patent and Trademark Office:

U.S. PATENT APPLICATION NO or U.S. PATENT NO.	FILING or GRANT DATE	TITLE
8,680,657	03/25/2014	LEAD FRAME, SEMICONDUCTOR APPARATUS USING THIS LEAD FRAME, INTERMEDIATE PRODUCT THEREOF AND MANUFACTURING METHOD THEREOF
8,349,656	01/08/2013	MANUFACTURING METHOD OF LEADFRAME AND SEMICONDUCTOR DEVICE
8,258,608	09/04/2012	LEAD FRAME AND INTERMEDIATE PRODUCT OF SEMICONDUCTOR DEVICE

WHEREAS ADVANCED SEMICONDUCTOR ENGINEERING, INC., of 26 CHIN 3RD ROAD, NANTZE EXPORT PROCESSING ZONE, KAOHSIUNG, Taiwan (hereinafter referred to as "Assignee") is desirous of acquiring the full right, title and interest in and to said inventions for the United States of America, and in and to said United States Letters Patents;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged by Assignor, Assignor has sold, assigned, transferred and set over, and by these presents hereby sells, assigns, transfers and sets over to Assignee the entire and exclusive right, title and interest in and to said inventions for the United States of America, and in and to said applications for Letters Patents listed above, including any and all divisional, continuation, continuation-in-part, reissues or extensions thereof, to be held and enjoyed by Assignee for its own use as fully and entirely as the same would have been held and enjoyed by Assignor had this assignment not been made; the Commissioner of Patents and Trademarks of the United States of America is hereby authorized to transfer the portion of the title indicated to said application to said Assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the Assignor, but also that such assigned rights are not encumbered by any grant, license, or other right theretofore given; Assignor hereby undertakes to execute and deliver to Assignee upon request all lawful documents which may be requested by Assignee, and to furnish Assignee with all facts relating to said invention as may be requested.

Atty. Dkt. No. 102351-0101

The undersigned hereby grant the firm of FOLEY & LARDNER LLP, the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

Date: 27 Sep 2018

MITSUI HIGH-TEC, INC.

By: [Signature]

Name: Yasunari Mitsui

Title President and Representative Director